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Front Matter: Volume 9736

, "Front Matter: Volume 9736," Proc. SPIE 9736, Laser-based Micro- and Nanoprocessing X, 973601 (11 May 2016); doi: 10.1117/12.2239299

SPIE.

Event: SPIE LASE, 2016, San Francisco, California, United States

PROCEEDINGS OF SPIE

Laser-based Micro- and Nanoprocessing X

**Udo Klotzbach
Kunihiko Washio
Craig B. Arnold**
Editors

**16–18 February 2016
San Francisco, California, United States**

Sponsored and Published by
SPIE

Volume 9736

Proceedings of SPIE 0277-786X, V. 9736

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Laser-based Micro- and Nanoprocessing X, edited by Udo Klotzbach, Kunihiko Washio, Craig B. Arnold,
Proc. of SPIE Vol. 9736, 973601 · © 2016 SPIE · CCC code: 0277-786X/16/\$18 · doi: 10.1117/12.2239299

Proc. of SPIE Vol. 9736 973601-1

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Author(s), "Title of Paper," in *Laser-based Micro- and Nanoprocessing X*, edited by Udo Klotzbach, Kunihiko Washio, Craig B. Arnold, Proceedings of SPIE Vol. 9736 (SPIE, Bellingham, WA, 2016) Six-digit Article CID Number.

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781628419719

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) • Fax +1 360 647 1445

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